

(b) Amendments to the Claims

Kindly cancel claims 11 and 22 without prejudice or disclaimer of subject matter.

Please amend claims 9 and 12 as follows. A detailed listing of all the claims in the application is provided.

1. (Original) A bonding system comprising:
a processing unit which processes surfaces of first and second substrates;
an operation unit which overlays the first and second substrates processed by said processing unit; and
a chamber which accommodates and isolates from an outer space said processing unit and operation unit,
wherein a process for the first and second substrates by said processing unit includes a process of cleaning and/or activating the surfaces of the first and second substrates.
2. (Original) The system according to claim 1, further comprising a filter, wherein an interior of said chamber is cleaned by said filter.
3. (Original) The system according to claim 1, further comprising a loader connected to said chamber, said loader including a mechanism which purges an atmosphere in said chamber.

4. (Original) The system according to claim 1, further comprising a mechanism which increases a pressure in said chamber to be higher than that outside said chamber.

5. (Original) The system according to claim 1, wherein the process for the first and second substrates by said processing unit includes a process of removing a moisture on the surfaces of the first and second substrates to a predetermined level.

6. (Original) The system according to claim 1, wherein the process for the first and second substrates by said processing unit includes a process of removing a moisture on the surfaces of the first and second substrates to a predetermined level and thereafter setting the moisture on the surfaces to a predetermined level so that a bonding strength of the first and second substrates increases.

7. (Original) The system according to claim 1, wherein said processing unit comprises a mechanism which removes a particle on the surfaces of the first and second substrates.

8. (Original) The system according to claim 1, wherein said processing unit comprises a mechanism which removes an organic substance on the surfaces of the first and second substrates.

9. (Currently Amended) The system according to claim 1, wherein said processing unit comprises a mechanism which sets an activation state of the surfaces of the first and second ~~substrate~~ substrates to a predetermined state.

10. (Original) The system according to claim 9, wherein said processing unit comprises a mechanism which activates the surfaces of the first and second substrates so that a bonding strength of the first and second substrates increases.

11. (Cancelled)

12. (Currently Amended) ~~A~~ The bonding system according to claim 1,
further comprising[[:]] a measurement unit in the chamber which measures a state of the
surfaces of the first and second substrates[[;]] and wherein a the processing unit ~~which~~
processes the surfaces of the first and second substrates on the basis of a measurement
result of said measurement unit[[;]]

~~an operation unit which overlays the first and second substrates processed
by said processing unit, and~~

~~a chamber which accommodates said measurement unit, processing unit,
and operation unit and isolates from an outer space;~~

~~wherein a process for the first and second substrates by said processing unit
includes a process of cleaning the surfaces of the first and second substrates.~~

13. (Original) The system according to claim 12, further comprising a
determination unit which checks whether or not the measurement result of said
measurement unit is within a predetermined range, wherein the process by said processing
unit is performed when said determination unit determines that the measurement result is
not within the predetermined range.

14. (Original) The system according to claim 12, further comprising a filter, wherein an interior of said chamber is cleaned by said filter.

15. (Original) The system according to claim 12, further comprising a loader connected to said chamber, said loader including a mechanism which purges an atmosphere in said chamber.

16. (Original) The system according to claim 12, further comprising a mechanism which increases a pressure in said chamber to be higher than that outside said chamber.

17. (Original) The system according to claim 12, wherein said processing unit comprises a mechanism which removes a particle on the surfaces of the first and second substrates.

18. (Original) The system according to claim 12, wherein said processing unit comprises a mechanism which removes an organic substance on the surfaces of the first and second substrates.

19. (Original) The system according to claim 12, wherein said processing unit comprises a mechanism which activates the surfaces of the first and second substrates so that a bonding strength of the first and second substrates increases.

20. (Original) The system according to claim 12, wherein the process for the first and second substrates by said processing unit includes a process of setting a moisture on the surfaces of the first and second substrates to a predetermined level so that a bonding strength of the first and second substrates increases.

21. (Original) The system according to claim 12, further comprising a humidity maintaining unit which maintains a humidity in said chamber to a substantially constant level.

22. (Cancelled)